



The European Institute for the PCB Community
Call for papers
EIPC Winter Conference Milan 2019
“European Technology for the global PCB/Electronics Industry”

Date: February 14 & 15, 2019
Conference location: NH Hotel Milano Fiera, Italy
Bonus Programme: Visit to Elga Europe

Presentations on the following topics can be included in the conference programme:

Keynote / Trends

- Business Outlook: Global Electronics Industry
- Automotive, E-mobility and High Rel application, Radar High Frequency
- Industrial Electronics, Lighting Transportation, Metal Core PCB, Space, Avionics-G5, Medical

Reliability /traceability requirements by Application

- Responsibility for Product Reliability and Safety
- Standards for Product Safety and Reliability
- Inhouse process control and conformation Testing
- Material and finish product Safety and Testing
- Advanced supply chain and Third party Testing

Tools for Reliability

- What Testing is needed and how to measure Reliability
- How to ensure product Safety and Reliability

Design & New Technologies

Success through Evolution- or Disruptive Technologies?

- PCBs in Polymer Technology
- Printed Electronics
- Material Technology- Laminate technologies - Coating technologies

Equipment evolution to meet Technology challenges

- Automation
- HMLV High Mix Low Volume
- Imaging and Printing
- ML-Pressing
- Controlled line etching, Copper thickness tolerances
- Embedding and Metal Core PCBs
- New technology, Innovations and Invention

Roadmapping on Automotive, Radar, Trains, Avionics, Lightening

- What input is provided through “Roadmap by market segments”
- Technology Guidance through market needs
- Adapting processes, materials, chemistry, equipments to future technology needs
- Strategic Partnership and planning for success through Networking

Learn how to master the challenges that impact the European Electronics Industry?

- ‘SLP’ (Substrates like PCB) are used in Asia for HDI PCBs in any layer technology
- ‘PLP’ (Panel Level Packaging) to reduce cost in WLP Wafer Level Packaging
- ‘SLP utilising MSAP’ (modified Semi- Additive processes)
- ‘TSP’ (Touch Screen Panel) and integrated touch OLED displays offers new types of PCBs
- ‘ELIC’ (Every Layer Interconnected) as right and rigid flex



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CALL FOR PAPERS

EIPC Winter Conference Milan – February 14 & 15, 2019

Topics

We invite you to submit a paper for one of the following topics:

- Management / Markets
 - Market forecasts and outlook
 - Status of the PCB industry today
 - Challenges and opportunities
 - EMS market data in Europe
- Embedding active and passive components
- EMS/ODM market & technology trends for Europe
- Material supply issues
- Soldering, Press-Fit insertion or Low temperature sintering
- New interconnect developments
- Added value European PCB manufacturing for the OEM base
 - Power electronics; interconnect and substrate performance requirements
 - PCB laminates; new materials for high frequency and thermal performance e.g. for LED lighting
 - Imaging / LDI processes and equipment
 - Novel materials and processes
- Latest developments in IMS PCBs
- Developments solderable surface finishes
- Yield improvement, copper waste, printed electronics, additive processes, laminate reduction
- High thermal conductivity substrates and power management applications
- New developments in imaging for reliable fine featured circuit boards
 - Advanced microvia metallisation processes
 - PCB Bio MEMS
 - Imaging
 - Plating
 - Inspection
- Manufacturing methods, Cleaning of PCBs/PCBAs, PCB services for OEM, Design for manufacturing
 - 3D printing & printed electronics
 - Technology demands for PCBs in renewable energy applications
 - Technology Roadmaps for various industry sectors: automotive, IT, defense, aerospace.
- Thermal management issues and solutions
- Drilling; laser and mechanical process developments
- Industry standards for meeting safety (flammability and electrical safety) requirements and/or manufacturing guidelines IPC, UL, IECs
- Reliability of PCBs and assemblies, measurement and testing methods
- Environmental issues and legislation, e.g. updates on REACH and RoHS, material scarcity, novel flame retardants, lifecycle approaches and recycling, safety; FR4.0 or FR4.1
- Pressfit technology + updated standards for Pressfit technology

Any other topic you feel may be of interest

Notes for speakers

The following guidelines are provided regarding the submittal of papers and how they are to be presented at the Conference:

- Papers should supply new technical, management or statistical information and not be presented for commercial purpose

- All presentations should be made in English. If the author has problems with presenting in English, he or she should inform EIPC about this situation.
- Presentations should not make direct comparisons with competitors' products.
- When the description of particular equipment is necessary for proper understanding of the process, it shall be confined to technical aspects.
- **Presentations will be required as a WRITTEN TEXT (Word/PDF) file**
- Illustrations, graphics, tables or pictures (including presenter's photograph) have to be electronically delivered in standard format and in the appropriate resolution (75 dpi for electronic publication)

The author or presenter of an oral presentation will be offered a complimentary one day conference registration, valid on the day the author is invited to present.

Abstract guidelines

Abstracts should include the following:

- Title of Presentation
- Author Listing; first/last name, affiliation, mailing address, telephone, fax, e-mail
- Abstract text (max. 200 words)
- Biography: brief background on the principal/presenting author (max. 100 words)

Acceptance Criteria

Abstracts will be reviewed by the Programme Committee, consisting of experts from within our industry. The official language of the Conference is English, **NO** simultaneous translations will be provided.

Selections will be based on the following criteria:

- Contribution to the industry.
- The abstract should clearly describe the nature, content, key points, and significance of the proposed paper.
- Presentations are to be strictly non-commercial and must focus on technical merits of described processes.
- Proprietary and/or confidentiality issues as well as approvals should be determined at time of submission.

Deadlines

- 1 page Abstract: **October 8, 2018**
- Paper submission: **December 17, 2018**

Please send the abstract submission form to:

Mrs. K. Smit-Westenberg email: kwestenberg@eipc.org

Sponsors:



For more information about sponsors or possibilities please have a look at the EIPC website www.eipc.org

Enquiries

Please send registration and/or sponsor enquiries to:

Mrs. K. Smit-Westenberg, email: kwestenberg@eipc.org

